

# Global Leading Manufacturer of High Thermal Conductivity IMS CCL

**High Thermal Conductivity IMS CCL Datasheet** 

# 广东博秘电子有限公司

**GuangDong BOYU Electronics CO.,Ltd** 



#### GUANGDONG BOYU 广系博秘



#### ntroduction

**G**uangdong BOYU Electronics Co., Ltd, is a high-tech enterprise which integrates R&D, production, service and one-stop solutions and concentrates on providing high-quality products of Aluminum and Copper Based CCL and special metal CCL to our customers.

The company has been awarded a series of international certifications such as ISO, UL, SGS, IATF16949 and ROHS.

The company is committed to the global market and has successfully exported products to Europe, USA, Southeast Asia and other countries and regions.

The company adheres to the business strategy of "Using the most advanced technology, Training high-quality employees, Manufacturing high-quality products", striving for innovation and contributing to the development of new technology and new materials for the electronic industry.

#### 产品应用

汽车内、外部照明系统

Automotive interior and exterior lighting system

新能源 IGBT

New energy automotive IGBT

汽车充电系统

Automotive charging system

工控散热方案

Industrial cooling solutions

矿机

Mine machine

#### 产品特性

高导热特性

High thermal conductivity

出色的耐热性

**Excellent heat resistance** 

符合 RoHS 要求

Meet the RoHS requirements

无卤素板材

Halogen-free

UL E513122

**U**L E513122

符合 UL 94V-0

Comply with UL 94V-0





## AL-01-B30 产品性能表

性能 PROPERTIES	测试方法 TEST METHOD	单位 UNIT	指标值 INDICATOR	典型值 TYPICAL VALUES
热性能 THERMAL PROPERTI	ES			
绝缘层热导率 Thermal conductivity	ASTM D5470	W/m. K	-	3. 0
热阻 Thermal resistivity	ASTM D5470	°C*in²/W	-	0. 035
	DSC	$^{\circ}$	_	130
热分解温度 TD	TGA(Wt5%loss)	°C	≥360	380
最大操作温度 MOT	UL94	°C	_	130
热应力 Thermal stress	Solder floating 288℃	Minute	≥15	25
电性能 ELECTRICAL PROPE	RTIES			
体积电阻 Volume resistivity	IPC-TM-650 2.5.17	MΩ.cm	≥10 <sup>6</sup>	10 <sup>8</sup>
表面电阻 Surface resistivity	IPC-TM-650 2.5.17	MΩ	≥10 <sup>4</sup>	10 <sup>7</sup>
介电常数 Dielectric constant	IPC-TM-650 2.5.5.3	1MHz	-	4.8
耗损系数 Dissipation factor	IPC-TM-650 2.5.5.3	1MHz	-	<b>≤</b> 0.02
击穿电压 Breakdown voltage	IPC-TM-650 2.5.6.2	AC/KV	-	4.0 (75 µm) 4.5 (100µm) 6.0 (125µm)
耐电弧 Arc resistance	IPC-TM-650 2.5.1	S	≥60	120
机械性能 MECHANICAL PRO	PERTIES			
剥离强度 Peel strength	IPC-TM-650 2.4.8	Lb/in	≥8	8. 5
<del></del>	D-24/23	%	≤1.5	
Moisture absorption	IPC-TM-650 2.6.2.1			
机构评级&阻燃性 AGENCY	RATINGS&DURABILITY			
U.L.可燃性 U.L. Flammability	UL94	Class	V-0	V-0
相对漏电起痕指数(CTI)	IEC60112	V	≥600	600

Remarks: Typical value is based on specimen of 1.5mm AL \ 75 $\mu$ m dielectric

OUR VALUES Globalization Care Cooperation Win-Win

#### 高导热金属基覆铜板

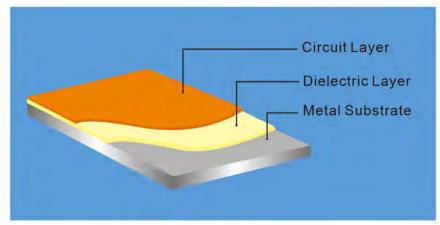
#### **High Thermal Conductivity IMS CCL**

#### 产品介绍

## **Introduction of products**

高导热金属基覆铜板能够针对不同的应用领域要求、各种铜厚、绝缘层特性、不同金属背板的需求,提供符合客户要求的高性价比产品。

For different areas of application requirements, various copper thickness, insulating layer characteristics and the need of different metal backboard, we can provide cost-effective metal based copper clad laminate with high thermal conductivity that meet customers' requirements.



#### 产品规格

### **Specification of products**

Standard BOYU Material Overview					
BOYU Material Type	AL-01-B30				
Thickness of Thermal	Mass Production	75、100、125			
Conductive (µm)	Sample	150			
Base Copper (µm)	Mass Production	18、35、70、105			
Dase Copper (µm)	Sample	140、210			
Aluminum Thickness (mm)	Mass Production	0.5-3.0			
Addininalii illickiless (lilli)	Sample	3.0-5.0			
Aluminum Type	Mass Production	5052			
Lamiante Size(mm)	Mass Production	460X610、510X610、533X610、500X600			
Lamante Size(min)	Sample	Specified (MOQ 100 sheet)			
Remark:	Finish thickness=Aluminum Thickness +Thickness of Thermal Conductive+Base Copper				

OUR VALUES Globalization Care Cooperation Win-Win



## 广东博秘电子有限公司

GuangDong BOYU Electronics Co., Ltd.

中国广东省惠州市惠澳大道惠南高新科技产业园民富路2号

2. Min-Fu R. D, HuiAo Street, South of Huizhou High-tech

Industrial Zone. Huizhou City, Guangdong Province, China.

TEL:0752-6811106 FAX: 0752-6811109

Http://www.boyu-global.com E-mail: sales@boyu-global.com

